MA27728

Silicon epitaxial planar type

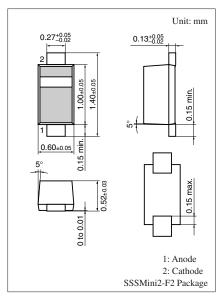
For switching circuits

■ Features

- High-density mounting is possible
- \bullet Low forward voltage V_F and good wave detection efficiency η
- Small temperature coefficient of forward characteristic
- Small reverse current I_R

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	30	V
Maximum peak reverse voltage	V_{RM}	30	V
Forward current	I_{F}	30	mA
Peak forward current	I_{FM}	150	mA
Junction temperature	Tj	125	°C
Storage temperature	T_{stg}	-55 to +125	°C

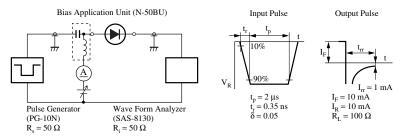


Marking Symbol: R

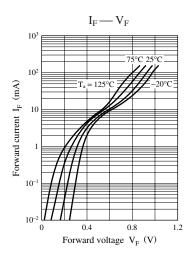
■ Electrical Characteristics $T_a = 25$ °C ± 3 °C

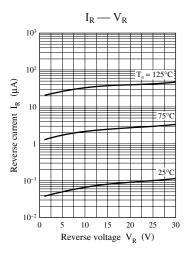
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	V _{F1}	$I_F = 1 \text{ mA}$			0.4	V
	V_{F2}	$I_F = 30 \text{ mA}$			1.0	
Reverse current	I_R	$V_R = 30 \text{ V}$			300	nA
Terminal capacitance	C _t	$V_R = 1 \text{ V, } f = 1 \text{ MHz}$		1.5		pF
Reverse recovery time *	t _{rr}	$I_F = I_R = 10 \text{ mA}$		1.0		ns
		$I_{rr} = 1 \text{ mA}, R_L = 100 \Omega$				
Detection efficiency	η	$V_{IN} = 3 V_{(peak)}$, $f = 30 MHz$		65		%
		$R_L = 3.9 \text{ k}\Omega, C_L = 10 \text{ pF}$				

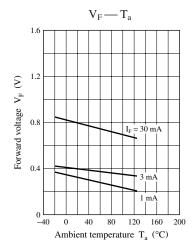
- Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
 - 2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
 - 3. Absolute frequency of input and output is 2 GHz
 - 4. *: t_{rr} measurement circuit

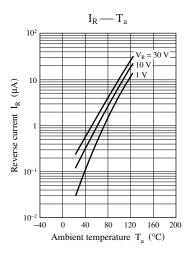


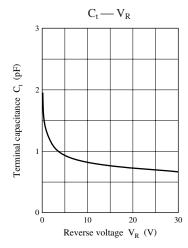
Panasonic

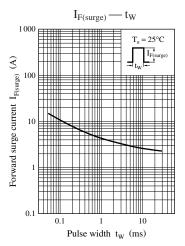












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